

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3818700

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	AMENDED AND RESTATED INTELLECTUAL PROPERTY AGREEMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHIPX, INCORPORATED	04/05/2016
RECEIVING PARTY DATA	
Name:	SILICON VALLEY BANK
Street Address:	2400 HANOVER STREET
City:	PALO ALTO
State/Country:	CALIFORNIA
Postal Code:	95134
PROPERTY NUMBERS Total: 5	
Property Type	Number
Patent Number:	7340705
Patent Number:	7500215
Patent Number:	7511536
Patent Number:	7675811
Patent Number:	7735041
CORRESPONDENCE DATA	
Fax Number:	(800)494-7512
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	202-370-4750
Email:	ipteam@nationalcorp.com
Correspondent Name:	DARLENA BARI STARK
Address Line 1:	1025 VERMONT AVE NW, SUITE 1130
Address Line 2:	NATIONAL CORPORATE RESEARCH, LTD.
Address Line 4:	WASHINGTON, D.C. 20005
ATTORNEY DOCKET NUMBER:	F162326
NAME OF SUBMITTER:	JAMES WON
SIGNATURE:	/James Won/
DATE SIGNED:	04/06/2016
Total Attachments: 9	

source=5. Closing Copy - Amended and Restated Intellectual Property Security Agreement - ChipX, Incorporated (#page1.tif
source=5. Closing Copy - Amended and Restated Intellectual Property Security Agreement - ChipX, Incorporated (#page2.tif
source=5. Closing Copy - Amended and Restated Intellectual Property Security Agreement - ChipX, Incorporated (#page3.tif
source=5. Closing Copy - Amended and Restated Intellectual Property Security Agreement - ChipX, Incorporated (#page4.tif
source=5. Closing Copy - Amended and Restated Intellectual Property Security Agreement - ChipX, Incorporated (#page5.tif
source=5. Closing Copy - Amended and Restated Intellectual Property Security Agreement - ChipX, Incorporated (#page6.tif
source=5. Closing Copy - Amended and Restated Intellectual Property Security Agreement - ChipX, Incorporated (#page7.tif
source=5. Closing Copy - Amended and Restated Intellectual Property Security Agreement - ChipX, Incorporated (#page8.tif
source=5. Closing Copy - Amended and Restated Intellectual Property Security Agreement - ChipX, Incorporated (#page9.tif

AMENDED AND RESTATED INTELLECTUAL PROPERTY SECURITY AGREEMENT

This Amended and Restated Intellectual Property Security Agreement (this "Agreement") is entered into as of April 5, 2016 by and between **SILICON VALLEY BANK**, a California corporation, with a loan production office located at 2400 Hanover Street, Palo Alto, California 95134 ("Bank") and **CHIPX, INCORPORATED**, a Delaware corporation, with its principal place of business located at 130 Baytech Drive, San Jose, CA 95134 ("Grantor").

RECITALS

A. Bank has agreed to make certain advances of money and to extend certain financial accommodations to Grantor, **GIGOPTIX, INC.**, a Delaware corporation, **ENDWAVE CORPORATION**, a Delaware corporation, and **MAGNUM SEMICONDUCTOR, INC.**, a Delaware corporation (jointly and severally, individually and collectively "Borrower") (the "Loans") in the amounts and manner set forth in that certain Third Amended and Restated Loan and Security Agreement by and between Bank and Grantor dated as of the date hereof (as the same may be amended, modified or supplemented from time to time, the "Loan Agreement"; capitalized terms used herein are used as defined in the Loan Agreement). Bank is willing to make the Loans to Borrower, but only upon the condition, among others, that Grantor shall grant to Bank a security interest in its Copyrights, Trademarks, Patents, and Mask Works (as each term is described below) to secure the obligations of Borrower to Bank.

B. Pursuant to the terms of the Loan Agreement, Grantor has granted to Bank a security interest in all of Grantor's right, title and interest, whether presently existing or hereafter acquired, in, to and under all of the Collateral.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, and intending to be legally bound, as collateral security for the prompt and complete payment when due of Borrower's obligations to Bank, Grantor hereby represents, warrants, covenants and agrees as follows:

AGREEMENT

1. Grant of Security Interest. To secure Borrower's obligations to Bank, Grantor grants and pledges to Bank a security interest in all of Grantor's right, title and interest in, to and under its intellectual property (all of which shall collectively be called the "Intellectual Property Collateral"), including, without limitation, the following:

(a) Any and all copyright rights, copyright applications, copyright registrations and like protections in each work of authorship and derivative work thereof, whether published or unpublished and whether or not the same also constitutes a trade secret, now or hereafter existing, created, acquired or held, including without limitation those set forth on Exhibit A attached hereto (collectively, the "Copyrights");

(b) Any and all trade secrets, and any and all intellectual property rights in computer software and computer software products now or hereafter existing, created, acquired or held;

(c) Any and all design rights that may be available to Grantor now or hereafter existing, created, acquired or held;

(d) All patents, patent applications and like protections including, without limitation, improvements, divisions, continuations, renewals, reissues, extensions and continuations-in-part of the same, including without limitation the patents and patent applications set forth on Exhibit B attached hereto (collectively, the "Patents");

(e) Any trademark and servicemark rights, whether registered or not, applications to register and registrations of the same and like protections, and the entire goodwill of the business of Grantor connected with and symbolized by such trademarks, including without limitation those set forth on Exhibit C attached hereto (collectively, the "Trademarks");

(f) All mask works or similar rights available for the protection of semiconductor chips, now owned or hereafter acquired, including, without limitation those set forth on Exhibit D attached hereto (collectively, the "Mask Works");

(g) Any and all claims for damages by way of past, present and future infringements of any of the rights included above, with the right, but not the obligation, to sue for and collect such damages for said use or infringement of the intellectual property rights identified above;

(h) All licenses or other rights to use any of the Copyrights, Patents, Trademarks, or Mask Works and all license fees and royalties arising from such use to the extent permitted by such license or rights;

(i) All amendments, extensions, renewals and extensions of any of the Copyrights, Trademarks, Patents, or Mask Works; and

(j) All proceeds and products of the foregoing, including without limitation all payments under insurance or any indemnity or warranty payable in respect of any of the foregoing.

2. Recordation. Grantor authorizes the Commissioner for Patents, the Commissioner for Trademarks and the Register of Copyrights and any other government officials to record and register this Agreement upon request by Bank.

3. Loan Documents. This Agreement has been entered into pursuant to and in conjunction with the Loan Agreement, which is hereby incorporated by reference. The provisions of the Loan Agreement shall supersede and control over any conflicting or inconsistent provision herein. The rights and remedies of Bank with respect to the Intellectual Property Collateral are as provided by the Loan Agreement and related documents, and nothing in this Agreement shall be deemed to limit such rights and remedies.

4. Execution in Counterparts. This Agreement may be executed in counterparts (and by different parties hereto in different counterparts), each of which shall constitute an original, but all of which when taken together shall constitute a single contract. Delivery of an executed counterpart of a signature page to this Agreement by facsimile or in electronic (i.e., "pdf" or "tif" format) shall be effective as delivery of a manually executed counterpart of this Agreement.

5. Successors and Assigns. This Agreement will be binding on and shall inure to the benefit of the parties hereto and their respective successors and assigns.

6. Governing Law. This Agreement and any claim, controversy, dispute or cause of action (whether in contract or tort or otherwise) based upon, arising out of or relating to this Agreement and the transactions contemplated hereby and thereby shall be governed by, and construed in accordance with, the

laws of the United States and the State of California, without giving effect to any choice or conflict of law provision or rule (whether of the State of California or any other jurisdiction).

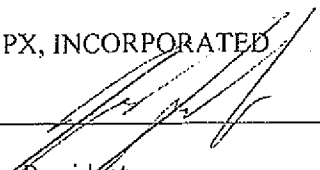
7. Amended and Restated Agreement. This Agreement amends and restates, and replaces, that certain Intellectual Property Security Agreement dated on or about April 23, 2010, between Grantor and Bank, as amended.

[Signature page follows.]

IN WITNESS WHEREOF, the parties have caused this Intellectual Property Security Agreement to be duly executed by its officers thereunto duly authorized as of the first date written above.

GRANTOR:

CHIPX, INCORPORATED

By:  _____

Title: President

BANK:

SILICON VALLEY BANK

By: _____

Title: _____

IN WITNESS WHEREOF, the parties have caused this Intellectual Property Security Agreement to be duly executed by its officers thereunto duly authorized as of the first date written above.

GRANTOR:

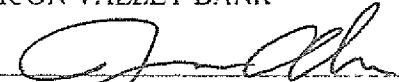
CHIPX, INCORPORATED

By: _____

Title: _____

BANK:

SILICON VALLEY BANK

By:  _____

Title: Vice President

SCHEDULE A

ChipX, Incorporated - Copyrights

RECORDATION NO.	RECORDATION DATE	TITLE
V3586D908	2010-02-09	QYH410.MW 8-844.
V3573D523	2009-02-02	QYH410. MW 8-844.

SCHEDULE B

ChipX, Incorporated - U.S. Patents

PATENT NO.	ISSUE DATE	TITLE
7,340,705	2008-03-04	In-circuit device, system and method to parallelize design and verification of application-specific integrated circuits ("ASICs") having embedded specialized function circuits
7,500,215	2009-03-03	Method of developing application-specific integrated circuit devices
7,511,536	2009-03-31	Cells of a customizable logic array device having independently accessible circuit elements
7,675,811	2010-03-09	Method and apparatus for DQS postamble detection and drift compensation in a double data rate (DDR) physical interface
7,735,041	2010-06-08	Methods and computer readable media implementing a modified routing grid to increase routing densities of customizable logic array devices

ChipX, Incorporated - U.S. Patent Applications

APPLICATION NO.	FILING DATE	TITLE
12/082,100	2008-04-07	Method and apparatus for DQS postamble detection and drift compensation in a double data rate (DDR) physical interface

SCHEDULE C

ChipX, Incorporated - U.S. Trademarks

REGISTRATION NO.	REGISTRATION DATE	TRADEMARK
3261924	2007-07-10	CHIP X

EXHIBIT D

Mask Works

Description

Registration/
Application
Number

Registration/
Application
Date

1959606.1